

# CD4020B, CD4024B, CD4040B Types

## CMOS Ripple-Carry Binary Counter/Dividers

High-Voltage Types (20-Volt Rating)

CD4020B – 14 Stage

CD4024B – 7 Stage

CD4040B – 12 Stage

■ CD4020B, CD4024B, and CD4040B are ripple-carry binary counters. All counter stages are master-slave flip-flops. The state of a counter advances one count on the negative transition of each input pulse; a high level on the RESET line resets the counter to its all zeros state. Schmitt trigger action on the input-pulse line permits unlimited rise and fall times. All inputs and outputs are buffered.

The CD4020B and CD4040B types are supplied in 16-lead hermetic dual-in-line ceramic packages (F3A suffix), 16-lead dual-in-line plastic packages (E suffix), 16-lead small-outline packages (NSR suffix), and 16-lead thin shrink small-outline packages (PW and PWR suffixes). The CD4040B type also is supplied in 16-lead small-outline packages (M and M96 suffixes).

The CD4024B types are supplied in 14-lead hermetic dual-in-line ceramic packages (F3A suffix), 14-lead dual-in-line plastic packages (E suffix), 14-lead small-outline packages (M, MT, M96, and NSR suffixes), and 14-lead thin shrink small-outline packages (PW and PWR suffixes).

**MAXIMUM RATINGS, Absolute-Maximum Values:**  
DC SUPPLY-VOLTAGE RANGE, ( $V_{DD}$ )

Voltages referenced to $V_{SS}$ Terminal	.....	-0.5V to +20V
INPUT VOLTAGE RANGE, ALL INPUTS	.....	-0.5V to $V_{DD}$ +0.5V
DC INPUT CURRENT, ANY ONE INPUT	.....	±10mA
POWER DISSIPATION PER PACKAGE ( $P_D$ ):		
For $T_A = -55^{\circ}\text{C}$ to $+100^{\circ}\text{C}$	.....	500mW
For $T_A = +100^{\circ}\text{C}$ to $+125^{\circ}\text{C}$	.....	Derate Linearly at 12mW/ $^{\circ}\text{C}$ to 200mW
DEVICE DISSIPATION PER OUTPUT TRANSISTOR		
FOR $T_A = \text{FULL PACKAGE-TEMPERATURE RANGE (All Package Types)}$	.....	100mW
OPERATING-TEMPERATURE RANGE ( $T_A$ )	.....	$-55^{\circ}\text{C}$ to $+125^{\circ}\text{C}$
STORAGE TEMPERATURE RANGE ( $T_{stg}$ )	.....	$-65^{\circ}\text{C}$ to $+150^{\circ}\text{C}$
LEAD TEMPERATURE (DURING SOLDERING):		
At distance $1/16 \pm 1/32$ inch ( $1.59 \pm 0.79\text{mm}$ ) from case for 10s max	.....	$+265^{\circ}\text{C}$

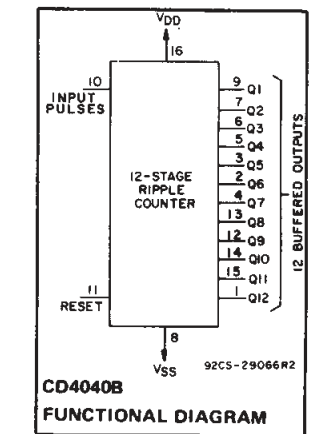
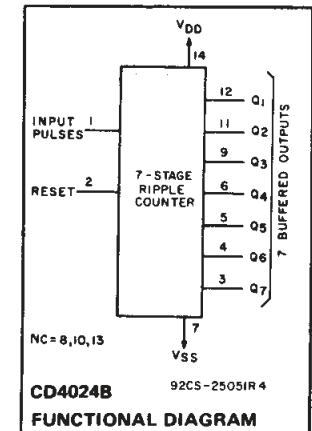
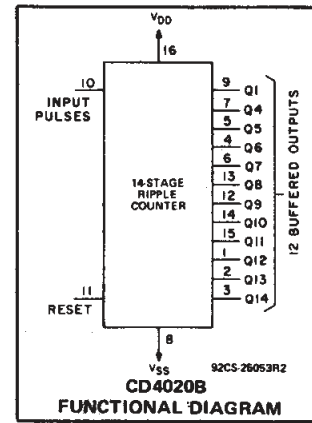
**Features:**

- Medium-speed operation
- Fully static operation
- Buffered inputs and outputs
- 100% tested for quiescent current at 20 V
- Standardized, symmetrical output characteristics
- Fully static operation
- Common reset
- 5-V, 10-V, and 15-V parametric ratings
- Maximum input current of 1  $\mu\text{A}$  at 18 V over full package-temperature range; 100 nA at 18 V and  $25^{\circ}\text{C}$
- Noise margin (over full package-temperature range):
  - 1 V at  $V_{DD} = 5\text{ V}$
  - 2 V at  $V_{DD} = 10\text{ V}$
  - 2.5 V at  $V_{DD} = 15\text{ V}$

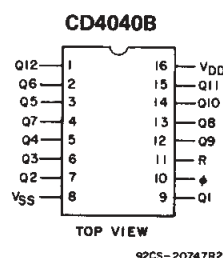
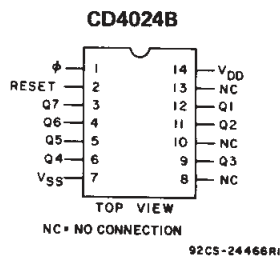
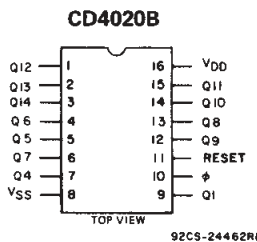
■ Meets all requirements of JEDEC Tentative Standard No. 13B, "Standard Specifications for Description of 'B' Series CMOS Devices"

**Applications:**

- Control counters
- Timers
- Frequency dividers
- Time-delay circuits



**TERMINAL ASSIGNMENTS**



# CD4020B, CD4024B, CD4040B Types

**RECOMMENDED OPERATING CONDITIONS** at  $T_A = 25^\circ\text{C}$ , Unless Otherwise Specified  
 For maximum reliability, nominal operating conditions should be selected so that operation is always within the following ranges:

CHARACTERISTIC	$V_{DD}$	Min.	Max.	UNITS
Supply Voltage Range (at $T_A = \text{Full Package-Temperature Range}$ )		3	18	V
Input-Pulse Frequency, $f_\phi$	5 10 15	—	3.5 8 12	MHz
Input-Pulse Width, $t_W$	5 10 15	140 60 40	— — —	ns
Input-Pulse Rise or Fall Time, $t_{r\phi}, t_{f\phi}$	5 10 15	Unlimited		$\mu\text{s}$
Reset Pulse Width, $t_W$	5 10 15	200 80 60	—	ns
Reset Removal Time, $t_{REM}$	5 10 15	350 150 100	—	ns

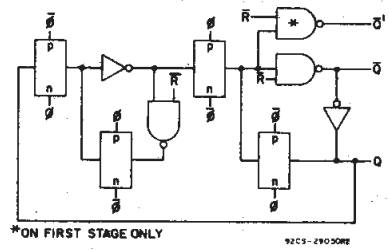


Fig. 4 - Detail of typical flip-flop stage.

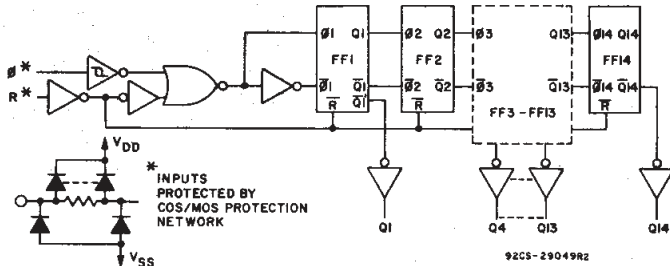


Fig. 1 - Logic diagram for CD4020B.

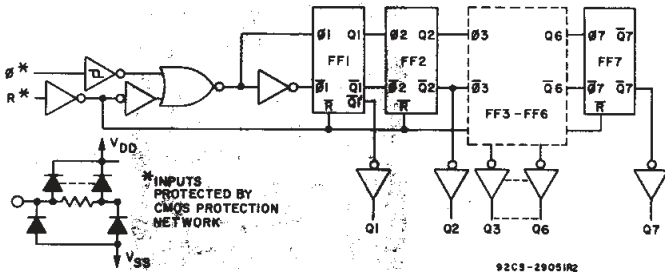


Fig. 2 - Logic diagram for CD4024B.

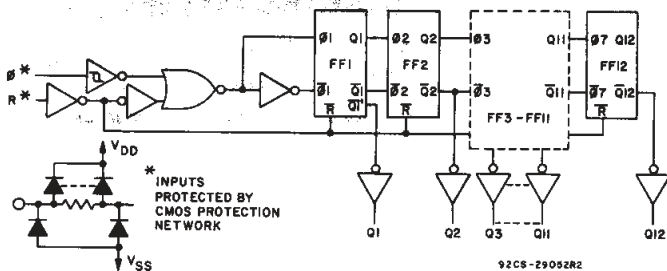


Fig. 3 - Logic diagram for CD4040B.

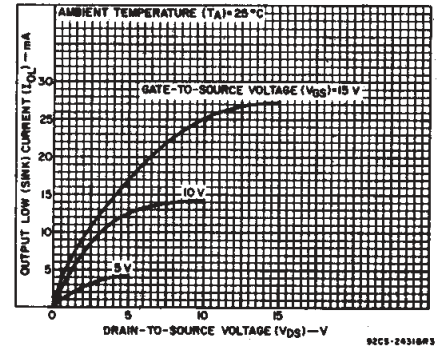


Fig. 5 - Typical output low (sink) current characteristics.

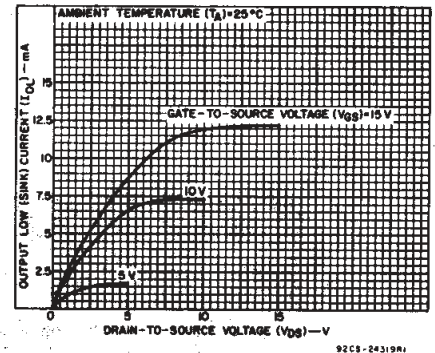


Fig. 6 - Minimum output low (sink) current characteristics.

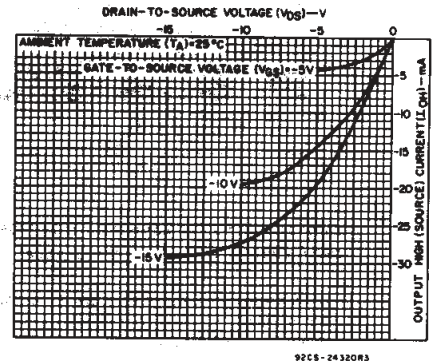


Fig. 7 - Typical output high (source) current characteristics.

**3**  
 COMMERCIAL CMOS  
 HIGH VOLTAGE ICs

# CD4020B, CD4024B, CD4040B Types

## STATIC ELECTRICAL CHARACTERISTICS

CHARACTERISTIC	CONDITIONS			LIMITS AT INDICATED TEMPERATURES (°C)							UNITS
	V <sub>O</sub> (V)	V <sub>IN</sub> (V)	V <sub>DD</sub> (V)	-55	-40	+85	+125	+25			
								Min.	Typ.	Max.	
Quiescent Device Current, I <sub>DD</sub> Max.	-	0.5	5	5	5	150	150	-	0.04	5	μA
	-	0.10	10	10	10	300	300	-	0.04	10	
	-	0.15	15	20	20	600	600	-	0.04	20	
	-	0.20	20	100	100	3000	3000	-	0.08	100	
Output Low (Sink) Current I <sub>OL</sub> Min.	0.4	0.5	5	0.64	0.61	0.42	0.36	0.51	1	-	mA
	0.5	0.10	10	1.6	1.5	1.1	0.9	1.3	2.6	-	
	1.5	0.15	15	4.2	4	2.8	2.4	3.4	6.8	-	
	-	-	-	-	-	-	-	-	-	-	
Output High (Source) Current, I <sub>OH</sub> Min.	4.6	0.5	5	-0.64	-0.61	-0.42	-0.36	-0.51	-1	-	mA
	2.5	0.5	5	-2	-1.8	-1.3	-1.15	-1.6	-3.2	-	
	9.5	0.10	10	-1.6	-1.5	-1.1	-0.9	-1.3	-2.6	-	
	13.5	0.15	15	-4.2	-4	-2.8	-2.4	-3.4	-6.8	-	
Output Voltage: Low-Level, V <sub>OL</sub> Max.	-	0.5	5	0.05				-	0	0.05	V
	-	0.10	10	0.05				-	0	0.05	
	-	0.15	15	0.05				-	0	0.05	
Output Voltage: High-Level, V <sub>OH</sub> Min.	-	0.5	5	4.95				4.95	5	-	V
	-	0.10	10	9.95				9.95	10	-	
	-	0.15	15	14.95				14.95	15	-	
Input Low Voltage, V <sub>IL</sub> Max.	0.5, 4.5	-	5	1.5				-	-	1.5	V
	1, 9	-	10	3				-	-	3	
	1.5, 13.5	-	15	4				-	-	4	
Input High Voltage, V <sub>IH</sub> Min.	0.5, 4.5	-	5	3.5				3.5	-	-	V
	1, 9	-	10	7				7	-	-	
	1.5, 13.5	-	15	11				11	-	-	
Input Current I <sub>IN</sub> Max.	-	0.18	18	±0.1	±0.1	±1	±1	-	±10 <sup>-5</sup>	±0.1	μA

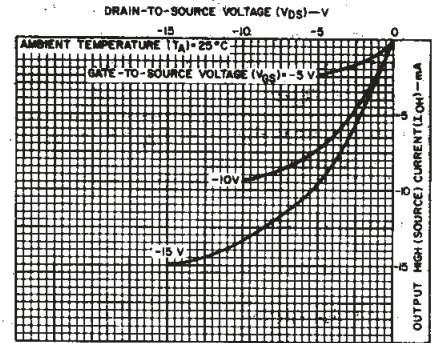


Fig. 8 - Minimum output high (source) current characteristics.

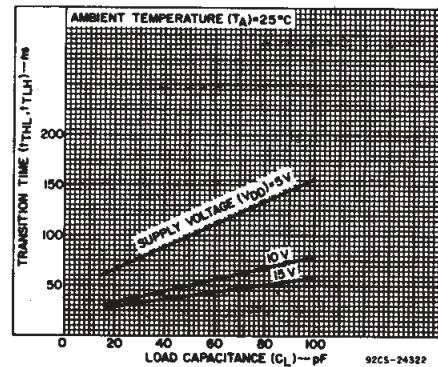
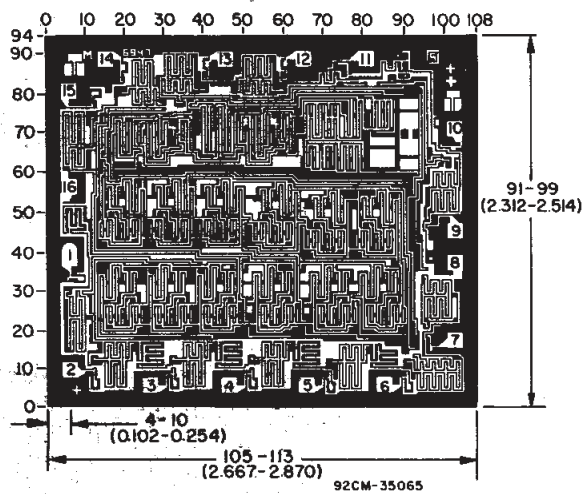
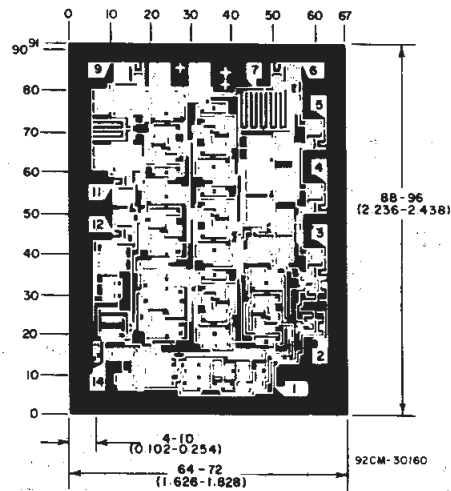


Fig. 9 - Typical transition time as a function of load capacitance.



Dimensions and Pad Layout for CD4020BH. Dimensions and pad layout for CD4040BH are identical.

Dimensions in parentheses are in millimeters and are derived from the basic inch dimensions as indicated. Grid graduations are in mils (10<sup>-3</sup> inch).



Dimensions and Pad Layout for CD4024BH.

# CD4020B, CD4024B, CD4040B Types

**DYNAMIC ELECTRICAL CHARACTERISTICS** at  $T_A = 25^\circ\text{C}$ , Input  $t_r, t_f = 20 \text{ ns}$ ,  
 $C_L = 50 \text{ pF}$ ,  $R_L = 200 \text{ k}\Omega$

CHARACTERISTIC	TEST CONDITIONS	$V_{DD}$ (V)	LIMITS			UNITS
			Min.	Typ.	Max.	
<b>Input-Pulse Operation</b>						
Propagation Delay Time, $\phi$ to $Q_1$ Out; $t_{PHL}, t_{PLH}$		5	—	180	360	ns
		10	—	80	160	
		15	—	65	130	
$Q_n$ to $Q_{n+1}$ ; $t_{PHL}, t_{PLH}$		5	—	100	330	ns
		10	—	40	80	
		15	—	30	60	
Transition Time, $t_{THL}, t_{TLH}$		5	—	100	200	ns
		10	—	50	100	
		15	—	40	80	
Minimum Input-Pulse Width, $t_W$		5	—	70	140	ns
		10	—	30	60	
		15	—	20	40	
Input-Pulse Rise or Fall Time, $t_{r\phi}, t_{f\phi}$		5	Unlimited			$\mu\text{s}$
		10	Unlimited			
		15	Unlimited			
Maximum Input-Pulse Frequency, $f_\phi$		5	3.5	7	—	MHz
		10	8	16	—	
		15	12	24	—	
Input Capacitance, $C_i$	Any Input		—	5	7.5	pF
<b>Reset Operation</b>						
Propagation Delay Time, $t_{PHL}$		5	—	140	280	ns
		10	—	60	120	
		15	—	50	100	
Minimum Reset Pulse Width, $t_W$		5	—	100	200	ns
		10	—	40	80	
		15	—	30	60	
Reset Removal Time, $t_{REM}$		5	—	175	350	ns
		10	—	75	150	
		15	—	50	100	

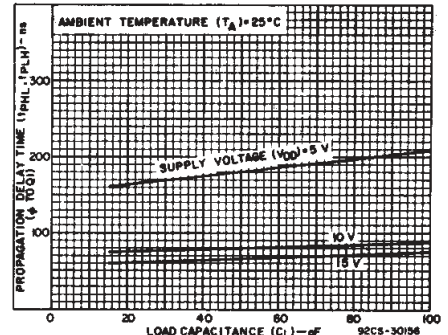


Fig. 10 – Typical propagation delay time as a function of load capacitance ( $\phi$  to  $Q_1$ ).

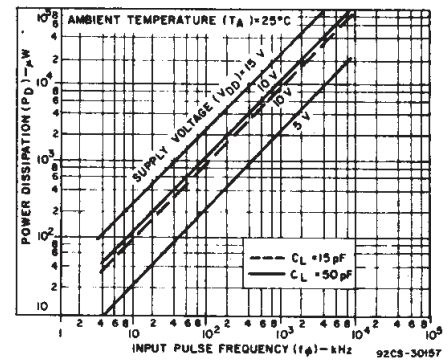


Fig. 11 – Typical dynamic power dissipation as a function of input pulse frequency for CD4020B.

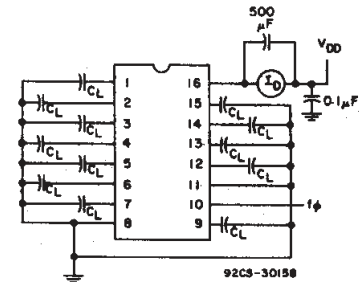


Fig. 12 – Dynamic power dissipation test circuit for CD4020B.

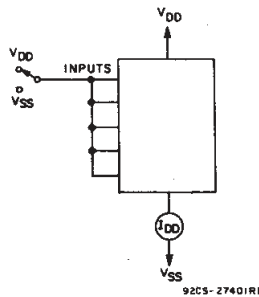


Fig. 13 – Quiescent device current test circuit.

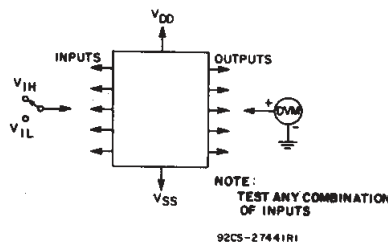


Fig. 14 – Input voltage test circuits.

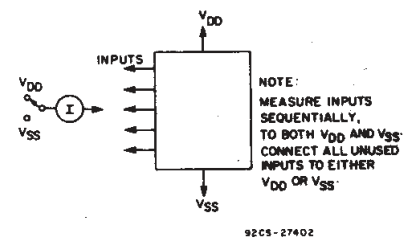


Fig. 15 – Input current test circuit.

3  
COMMERCIAL CMOS  
HIGH VOLTAGE ICs

**PACKAGING INFORMATION**

Orderable Device	Status <sup>(1)</sup>	Package Type	Package Drawing	Pins	Package Qty	Eco Plan <sup>(2)</sup>	Lead/Ball Finish	MSL Peak Temp <sup>(3)</sup>
89271AKB3T	OBSOLETE	CFP	WR	16		None	Call TI	Call TI
89274AKB3T	OBSOLETE	CFP	WR	16		None	Call TI	Call TI
CD4020BE	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	Level-NC-NC-NC
CD4020BF	ACTIVE	CDIP	J	16	1	None	Call TI	Level-NC-NC-NC
CD4020BF3A	ACTIVE	CDIP	J	16	1	None	Call TI	Level-NC-NC-NC
CD4020BNSR	ACTIVE	SO	NS	16	2000	Pb-Free (RoHS)	CU NIPDAU	Level-2-260C-1 YEAR/ Level-1-235C-UNLIM
CD4020BPW	ACTIVE	TSSOP	PW	16	90	Pb-Free (RoHS)	CU NIPDAU	Level-1-250C-UNLIM
CD4020BPWR	ACTIVE	TSSOP	PW	16	2000	Pb-Free (RoHS)	CU NIPDAU	Level-1-250C-UNLIM
CD4024BE	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	Level-NC-NC-NC
CD4024BF	ACTIVE	CDIP	J	14	1	None	Call TI	Level-NC-NC-NC
CD4024BF3A	ACTIVE	CDIP	J	14	1	None	Call TI	Level-NC-NC-NC
CD4024BM	ACTIVE	SOIC	D	14	50	Pb-Free (RoHS)	CU NIPDAU	Level-2-260C-1 YEAR/ Level-1-235C-UNLIM
CD4024BM96	ACTIVE	SOIC	D	14	2500	Pb-Free (RoHS)	CU NIPDAU	Level-2-260C-1 YEAR/ Level-1-235C-UNLIM
CD4024BMT	ACTIVE	SOIC	D	14	250	Pb-Free (RoHS)	CU NIPDAU	Level-2-260C-1 YEAR/ Level-1-235C-UNLIM
CD4024BNSR	ACTIVE	SO	NS	14	2000	Pb-Free (RoHS)	CU NIPDAU	Level-2-260C-1 YEAR/ Level-1-235C-UNLIM
CD4024BPW	ACTIVE	TSSOP	PW	14	90	Pb-Free (RoHS)	CU NIPDAU	Level-1-250C-UNLIM
CD4024BPWR	ACTIVE	TSSOP	PW	14	2000	Pb-Free (RoHS)	CU NIPDAU	Level-1-250C-UNLIM
CD4040BE	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	Level-NC-NC-NC
CD4040BF	ACTIVE	CDIP	J	16	1	None	Call TI	Level-NC-NC-NC
CD4040BF3A	ACTIVE	CDIP	J	16	1	None	Call TI	Level-NC-NC-NC
CD4040BM	ACTIVE	SOIC	D	16	40	Pb-Free (RoHS)	CU NIPDAU	Level-2-260C-1 YEAR/ Level-1-235C-UNLIM
CD4040BM96	ACTIVE	SOIC	D	16	2500	Pb-Free (RoHS)	CU NIPDAU	Level-2-260C-1 YEAR/ Level-1-235C-UNLIM
CD4040BNSR	ACTIVE	SO	NS	16	2000	Pb-Free (RoHS)	CU NIPDAU	Level-2-260C-1 YEAR/ Level-1-235C-UNLIM
CD4040BPW	ACTIVE	TSSOP	PW	16	90	Pb-Free (RoHS)	CU NIPDAU	Level-1-250C-UNLIM
CD4040BPWR	ACTIVE	TSSOP	PW	16	2000	Pb-Free (RoHS)	CU NIPDAU	Level-1-250C-UNLIM
JM38510/05653BEA	ACTIVE	CDIP	J	16	1	None	Call TI	Level-NC-NC-NC
JM38510/05655BCA	ACTIVE	CDIP	J	14	1	None	Call TI	Level-NC-NC-NC

<sup>(1)</sup> The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

<sup>(2)</sup> Eco Plan - May not be currently available - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

**None:** Not yet available Lead (Pb-Free).

**Pb-Free (RoHS):** TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

**Green (RoHS & no Sb/Br):** TI defines "Green" to mean "Pb-Free" and in addition, uses package materials that do not contain halogens, including bromine (Br) or antimony (Sb) above 0.1% of total product weight.

<sup>(3)</sup> MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

**Important Information and Disclaimer:** The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

J (R-GDIP-T\*\*)

14 LEADS SHOWN

CERAMIC DUAL IN-LINE PACKAGE



DIM \ PINS **	14	16	18	20
A	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC
B MAX	0.785 (19,94)	.840 (21,34)	0.960 (24,38)	1.060 (26,92)
B MIN	—	—	—	—
C MAX	0.300 (7,62)	0.300 (7,62)	0.310 (7,87)	0.300 (7,62)
C MIN	0.245 (6,22)	0.245 (6,22)	0.220 (5,59)	0.245 (6,22)



4040083/F 03/03

- NOTES:
- All linear dimensions are in inches (millimeters).
  - This drawing is subject to change without notice.
  - This package is hermetically sealed with a ceramic lid using glass frit.
  - Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
  - Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

N (R-PDIP-T\*\*)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



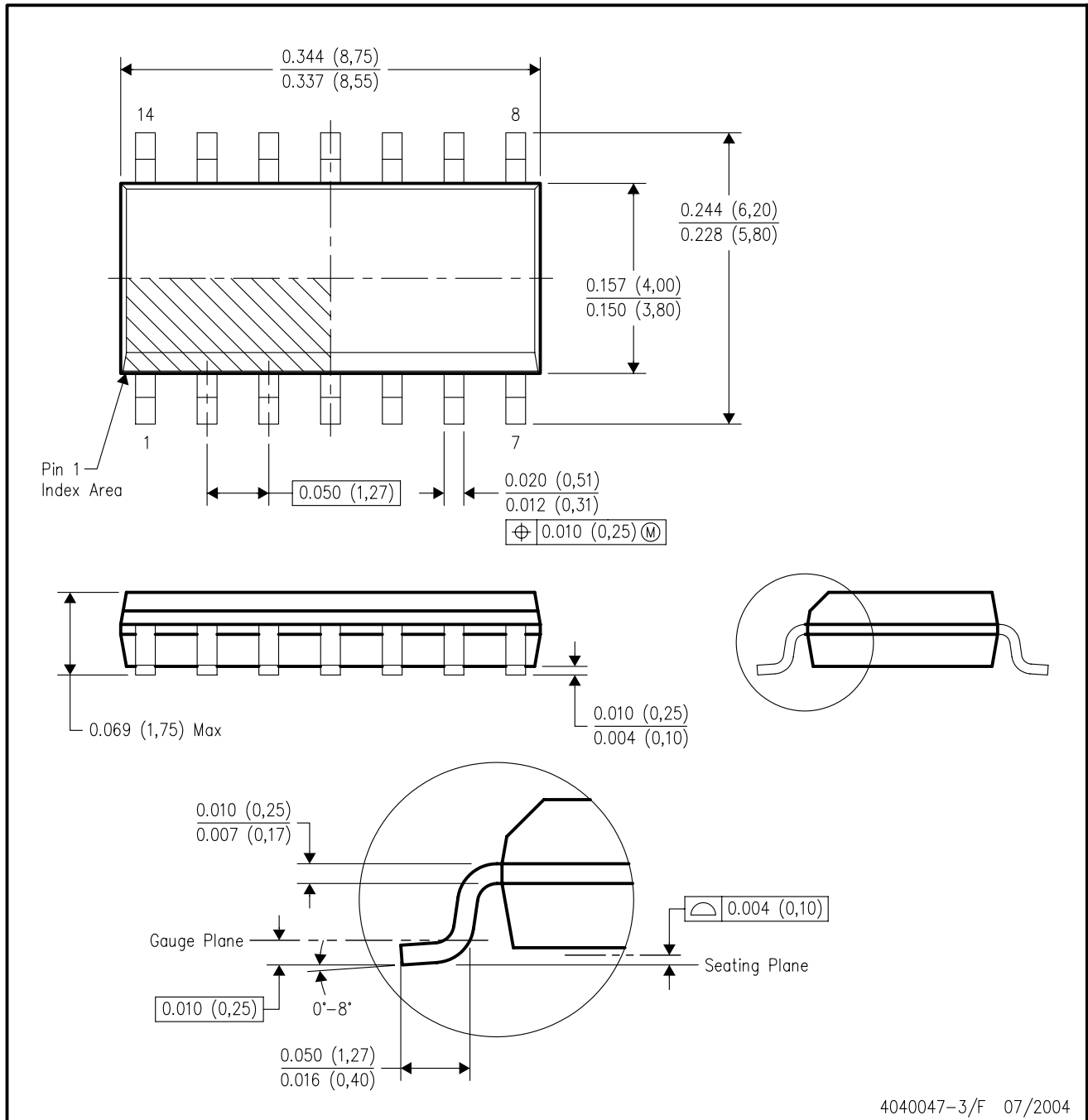
- NOTES:
- A. All linear dimensions are in inches (millimeters).
  - B. This drawing is subject to change without notice.
  - C Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
  - D The 20 pin end lead shoulder width is a vendor option, either half or full width.

4040049/E 12/2002



D (R-PDSO-G14)

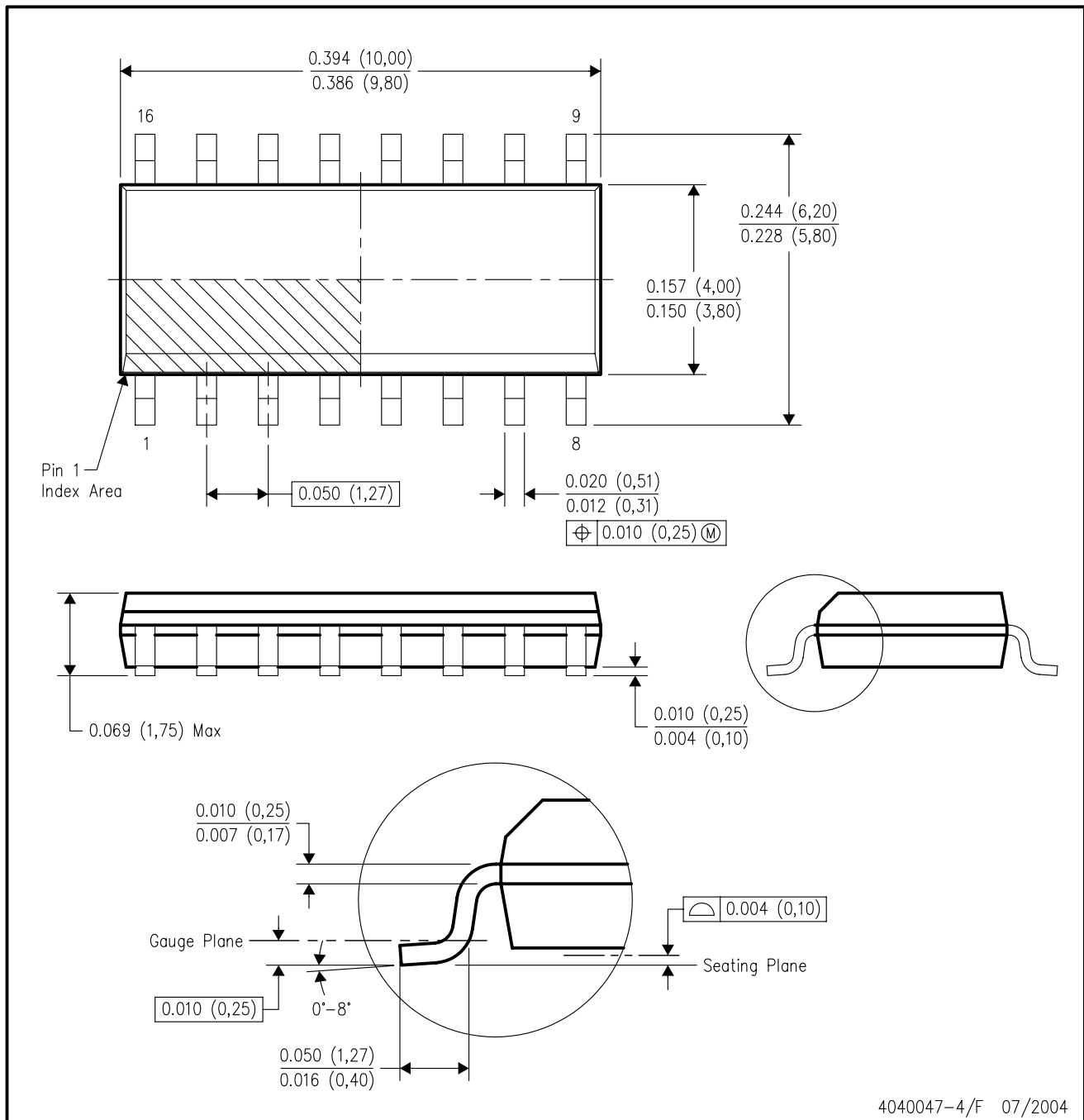
PLASTIC SMALL-OUTLINE PACKAGE



- NOTES:
- A. All linear dimensions are in inches (millimeters).
  - B. This drawing is subject to change without notice.
  - C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
  - D. Falls within JEDEC MS-012 variation AB.

D (R-PDSO-G16)

PLASTIC SMALL-OUTLINE PACKAGE



4040047-4/F 07/2004

- NOTES:
- A. All linear dimensions are in inches (millimeters).
  - B. This drawing is subject to change without notice.
  - C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
  - D. Falls within JEDEC MS-012 variation AC.

# MECHANICAL DATA

NS (R-PDSO-G\*\*)

PLASTIC SMALL-OUTLINE PACKAGE

14-PINS SHOWN

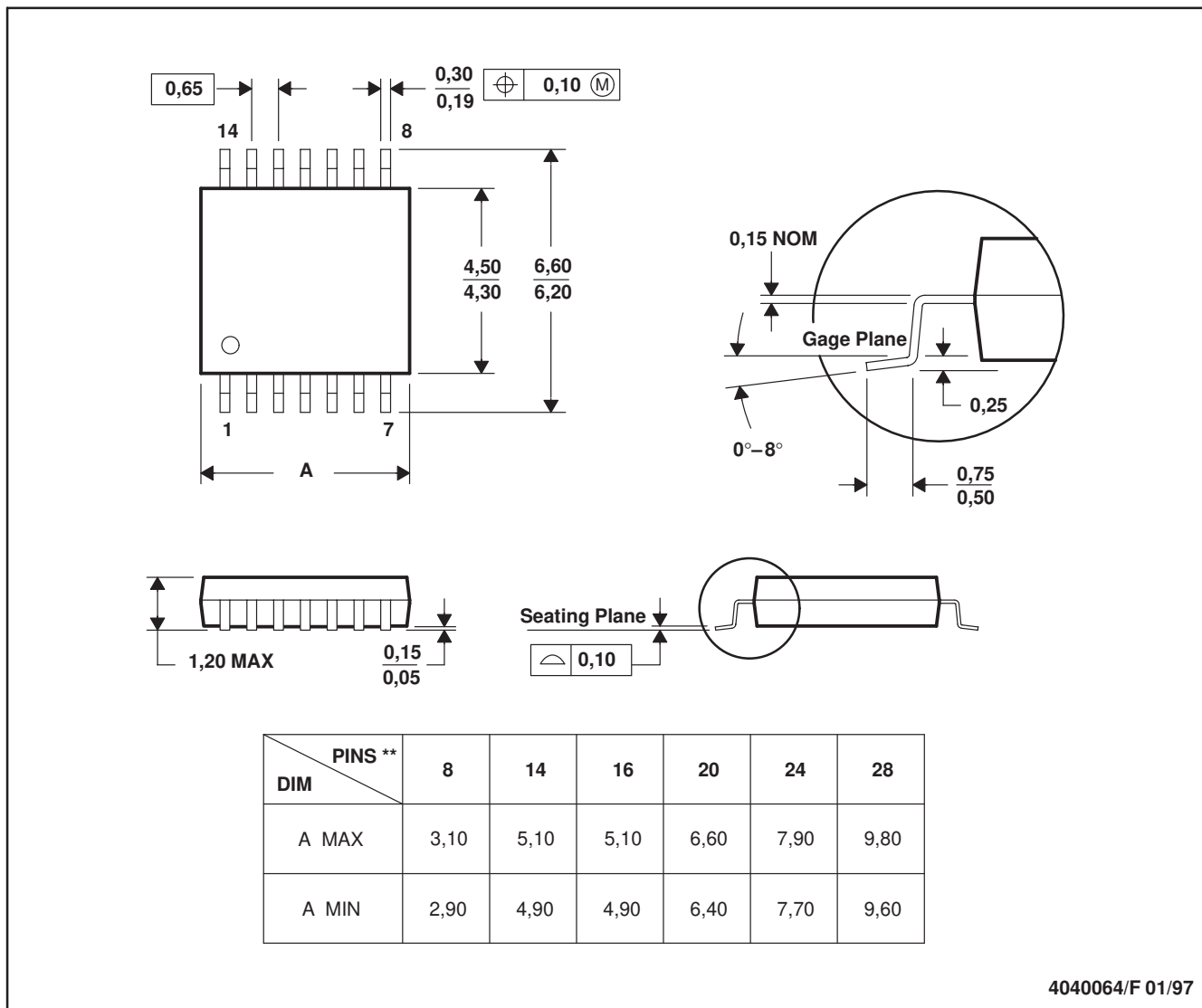


- NOTES:
- A. All linear dimensions are in millimeters.
  - B. This drawing is subject to change without notice.
  - C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

PW (R-PDSO-G\*\*)

PLASTIC SMALL-OUTLINE PACKAGE

14 PINS SHOWN



4040064/F 01/97

- NOTES: A. All linear dimensions are in millimeters.  
 B. This drawing is subject to change without notice.  
 C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.  
 D. Falls within JEDEC MO-153

## IMPORTANT NOTICE

Texas Instruments Incorporated and its subsidiaries (TI) reserve the right to make corrections, modifications, enhancements, improvements, and other changes to its products and services at any time and to discontinue any product or service without notice. Customers should obtain the latest relevant information before placing orders and should verify that such information is current and complete. All products are sold subject to TI's terms and conditions of sale supplied at the time of order acknowledgment.

TI warrants performance of its hardware products to the specifications applicable at the time of sale in accordance with TI's standard warranty. Testing and other quality control techniques are used to the extent TI deems necessary to support this warranty. Except where mandated by government requirements, testing of all parameters of each product is not necessarily performed.

TI assumes no liability for applications assistance or customer product design. Customers are responsible for their products and applications using TI components. To minimize the risks associated with customer products and applications, customers should provide adequate design and operating safeguards.

TI does not warrant or represent that any license, either express or implied, is granted under any TI patent right, copyright, mask work right, or other TI intellectual property right relating to any combination, machine, or process in which TI products or services are used. Information published by TI regarding third-party products or services does not constitute a license from TI to use such products or services or a warranty or endorsement thereof. Use of such information may require a license from a third party under the patents or other intellectual property of the third party, or a license from TI under the patents or other intellectual property of TI.

Reproduction of information in TI data books or data sheets is permissible only if reproduction is without alteration and is accompanied by all associated warranties, conditions, limitations, and notices. Reproduction of this information with alteration is an unfair and deceptive business practice. TI is not responsible or liable for such altered documentation.

Resale of TI products or services with statements different from or beyond the parameters stated by TI for that product or service voids all express and any implied warranties for the associated TI product or service and is an unfair and deceptive business practice. TI is not responsible or liable for any such statements.

Following are URLs where you can obtain information on other Texas Instruments products and application solutions:

<b>Products</b>		<b>Applications</b>	
Amplifiers	<a href="http://amplifier.ti.com">amplifier.ti.com</a>	Audio	<a href="http://www.ti.com/audio">www.ti.com/audio</a>
Data Converters	<a href="http://dataconverter.ti.com">dataconverter.ti.com</a>	Automotive	<a href="http://www.ti.com/automotive">www.ti.com/automotive</a>
DSP	<a href="http://dsp.ti.com">dsp.ti.com</a>	Broadband	<a href="http://www.ti.com/broadband">www.ti.com/broadband</a>
Interface	<a href="http://interface.ti.com">interface.ti.com</a>	Digital Control	<a href="http://www.ti.com/digitalcontrol">www.ti.com/digitalcontrol</a>
Logic	<a href="http://logic.ti.com">logic.ti.com</a>	Military	<a href="http://www.ti.com/military">www.ti.com/military</a>
Power Mgmt	<a href="http://power.ti.com">power.ti.com</a>	Optical Networking	<a href="http://www.ti.com/opticalnetwork">www.ti.com/opticalnetwork</a>
Microcontrollers	<a href="http://microcontroller.ti.com">microcontroller.ti.com</a>	Security	<a href="http://www.ti.com/security">www.ti.com/security</a>
		Telephony	<a href="http://www.ti.com/telephony">www.ti.com/telephony</a>
		Video & Imaging	<a href="http://www.ti.com/video">www.ti.com/video</a>
		Wireless	<a href="http://www.ti.com/wireless">www.ti.com/wireless</a>

Mailing Address: Texas Instruments  
Post Office Box 655303 Dallas, Texas 75265

Copyright © 2005, Texas Instruments Incorporated

This datasheet has been download from:

[www.datasheetcatalog.com](http://www.datasheetcatalog.com)

Datasheets for electronics components.